

**Features**

- Uses CRM(CQ) advanced SkyMOS1 technology
- Extremely low on-resistance  $R_{DS(on)}$
- Excellent  $Q_g \times R_{DS(on)}$  product(FOM)
- Qualified according to JEDEC criteria

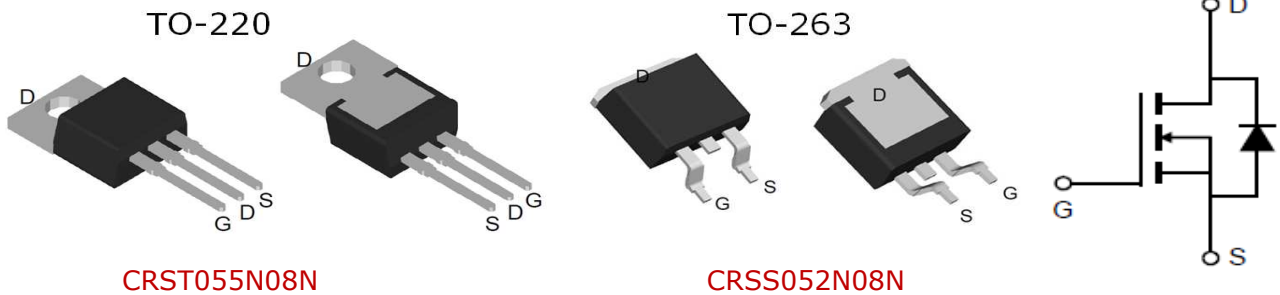
**Applications**

- Motor control and drive
- Battery management
- UPS (Uninterruptible Power Supplies)

**Product Summary**

$V_{DS}$	85V
$R_{DS(on)}$	4.6mΩ
$I_D$	120A

**100% Avalanche Tested**



CRST055N08N

CRSS052N08N

**Package Marking and Ordering Information**

Part #	Marking	Package	Packing	Reel Size	Tape Width	Qty
CRST055N08N	-	TO-220	Tube	N/A	N/A	50pcs
CRSS052N08N	-	TO-263	Tube	N/A	N/A	50pcs

**Absolute Maximum Ratings**

Parameter	Symbol	Value	Unit
Drain-source voltage	$V_{DS}$	85	V
Continuous drain current $T_C = 25^\circ\text{C}$ (Silicon limit) $T_C = 25^\circ\text{C}$ (Package limit) $T_C = 100^\circ\text{C}$ (Silicon limit)	$I_D$	135 120 86	A
Pulsed drain current ( $T_C = 25^\circ\text{C}$ , $t_p$ limited by $T_{jmax}$ )	$I_{D\ pulse}$	480	A
Avalanche energy, single pulse ( $L=0.5\text{mH}$ , $R_g=25\Omega$ )	$E_{AS}$	144	mJ
Gate-Source voltage	$V_{GS}$	$\pm 20$	V
Power dissipation ( $T_C = 25^\circ\text{C}$ )	$P_{tot}$	174	W
Operating junction and storage temperature	$T_j, T_{stg}$	-55...+150	$^\circ\text{C}$

**Thermal Resistance**

Parameter	Symbol	Max	Unit
Thermal resistance, junction – case.	$R_{thJC}$	0.72	°C/W
Thermal resistance, junction – ambient(min. footprint)	$R_{thJA}$	62	

**Electrical Characteristic (at  $T_j = 25\text{ }^\circ\text{C}$ , unless otherwise specified)**

Parameter	Symbol	Value			Unit	Test Condition
		min.	typ.	max.		

**Static Characteristic**

Drain-source breakdown voltage	$BV_{DSS}$	85	97	-	V	$V_{GS}=0V, I_D=250\mu A$
Gate threshold voltage	$V_{GS(th)}$	2	3	4	V	$V_{DS}=V_{GS}, I_D=250\mu A$
Zero gate voltage drain current	$I_{DSS}$	-	0.05	1	$\mu A$	$V_{DS}=80V, V_{GS}=0V$ $T_j=25^\circ C$ $T_j=125^\circ C$
Gate-source leakage current	$I_{GSS}$	-	10	100	nA	$V_{GS}=20V, V_{DS}=0V$
Drain-source on-state resistance	$R_{DS(on)}$	-	4.6	5.5	$m\Omega$	$V_{GS}=10V, I_D=50A$ TO-220 TO-263
		-	4.3	5.2		
Transconductance	$g_{fs}$	-	84.2	-	S	$V_{DS}=5V, I_D=50A$

**Dynamic Characteristic**

Input Capacitance	$C_{iss}$	-	3086	-	pF	$V_{GS}=0V, V_{DS}=40V,$ $f=1MHz$
Output Capacitance	$C_{oss}$	-	1057	-		
Reverse Transfer Capacitance	$C_{rss}$	-	26	-		
Gate Total Charge	$Q_G$	-	55	-	nC	$V_{GS}=10V, V_{DS}=40V,$ $I_D=50A, f=1MHz$
Gate-Source charge	$Q_{gs}$	-	15	-		
Gate-Drain charge	$Q_{gd}$	-	13	-		
Turn-on delay time	$t_{d(on)}$	-	20.1	-	ns	$V_{GS}=10V, V_{DD}=40V,$ $R_{G\_ext}=3.0\Omega$
Rise time	$t_r$	-	38.9	-		
Turn-off delay time	$t_{d(off)}$	-	45.1	-		
Fall time	$t_f$	-	22.8	-		
Gate resistance	$R_G$	-	3.3	-	$\Omega$	$V_{GS}=0V, V_{DS}=0V,$ $f=1MHz$

### Body Diode Characteristic

Parameter	Symbol	Value			Unit	Test Condition
		min.	typ.	max.		
Body Diode Forward Voltage	$V_{SD}$	-	0.95	1.4	V	$V_{GS}=0V, I_{SD}=50A$
Body Diode Reverse Recovery Time	$t_{rr}$	-	60	-	ns	$I_F=20A,$ $dI/dt=500A/\mu s$
Body Diode Reverse Recovery Charge	$Q_{rr}$	-	560	-	nC	

### Typical Performance Characteristics

Fig 1: Output Characteristics

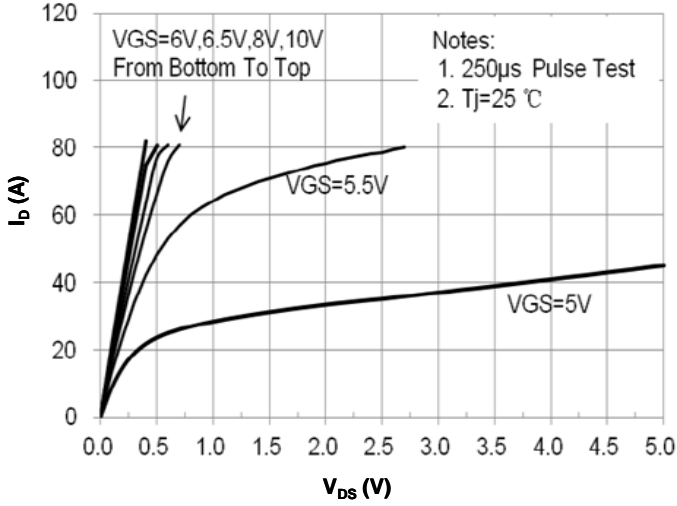


Fig 2: Transfer Characteristics

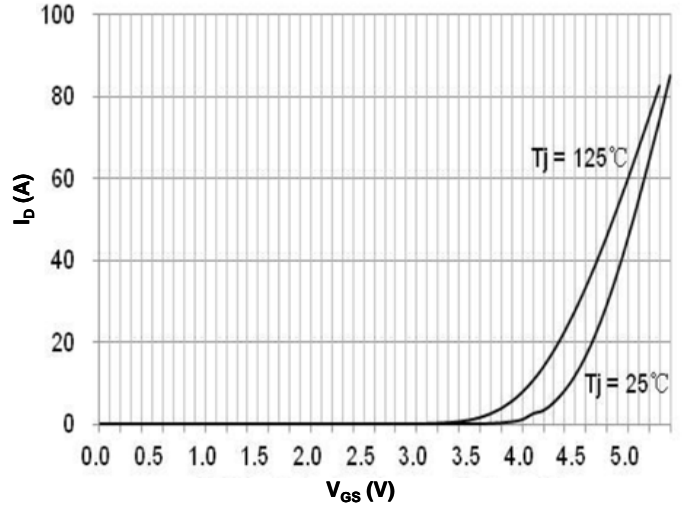


Fig 3: Rds(on) vs Drain Current and Gate Voltage

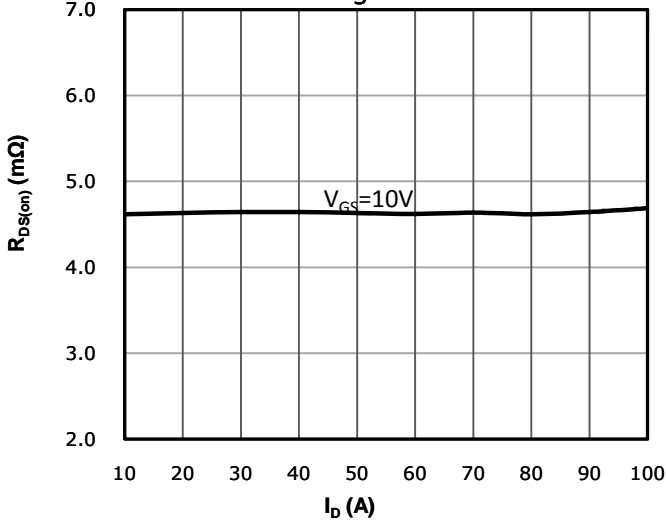


Fig 4: Rds(on) vs Gate Voltage

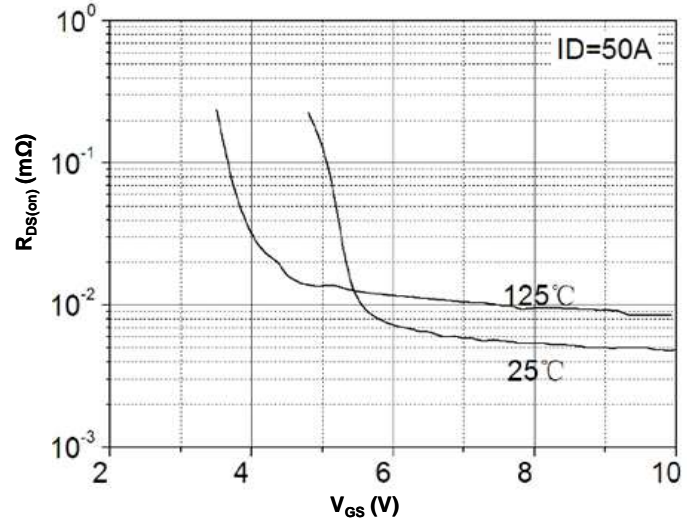


Fig 5: Rds(on) vs. Temperature

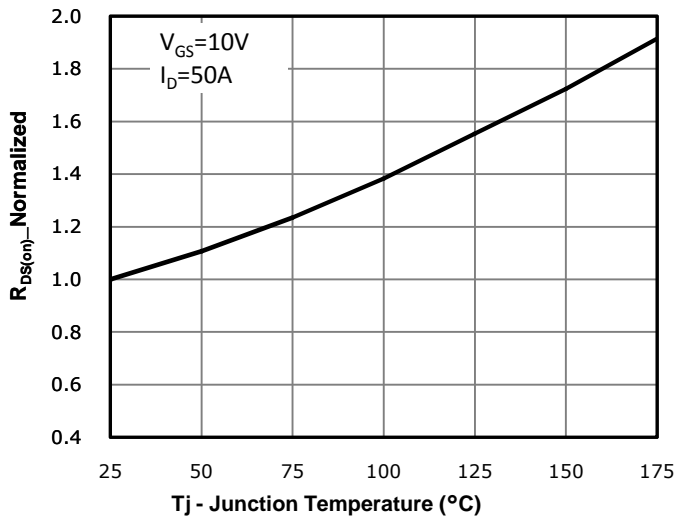


Fig 6: Capacitance Characteristics

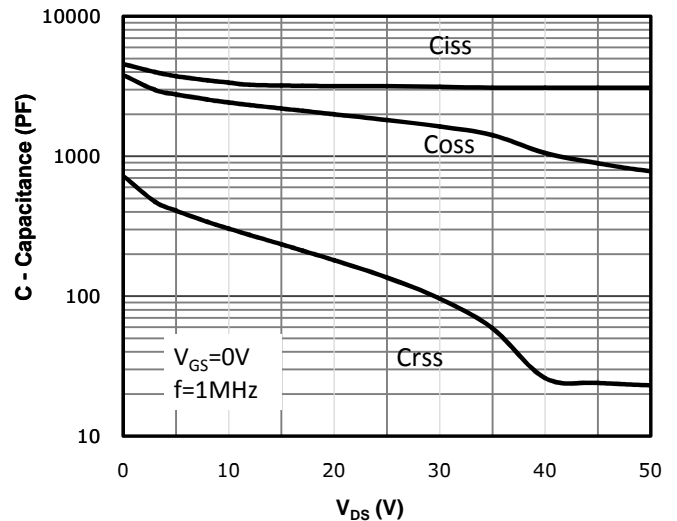


Fig 7: Gate Charge Characteristics

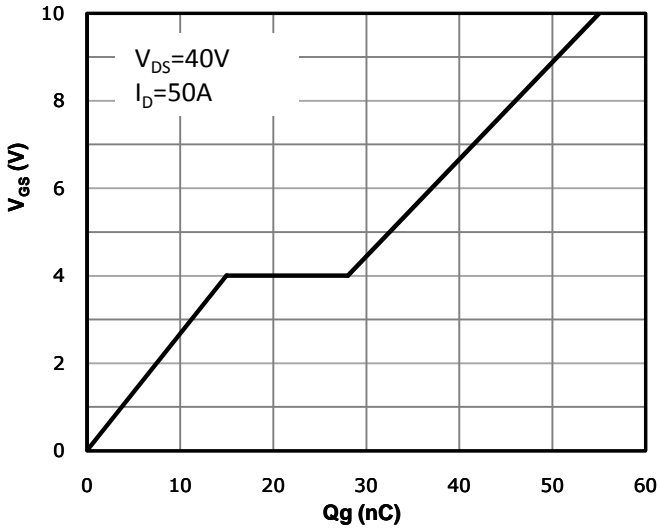


Fig 8: Body-diode Forward Characteristics

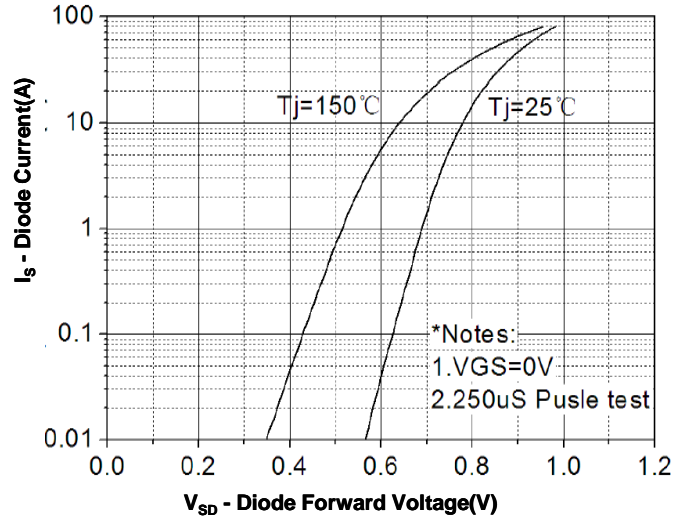


Fig 9: Power Dissipation

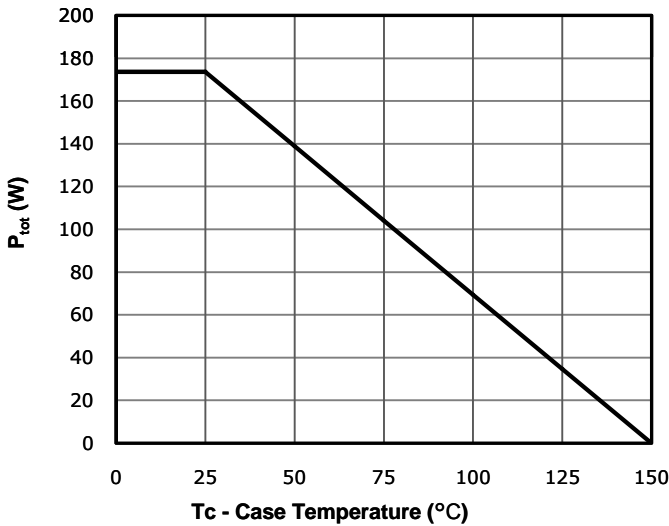


Fig 10: Drain Current Derating

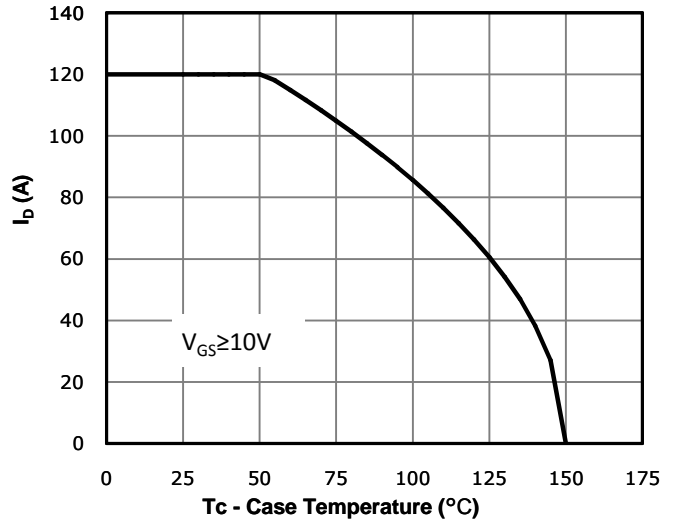


Fig 11: Safe Operating Area

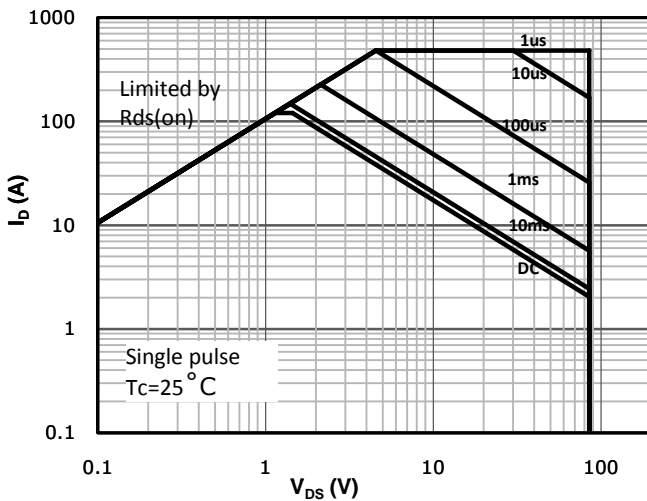
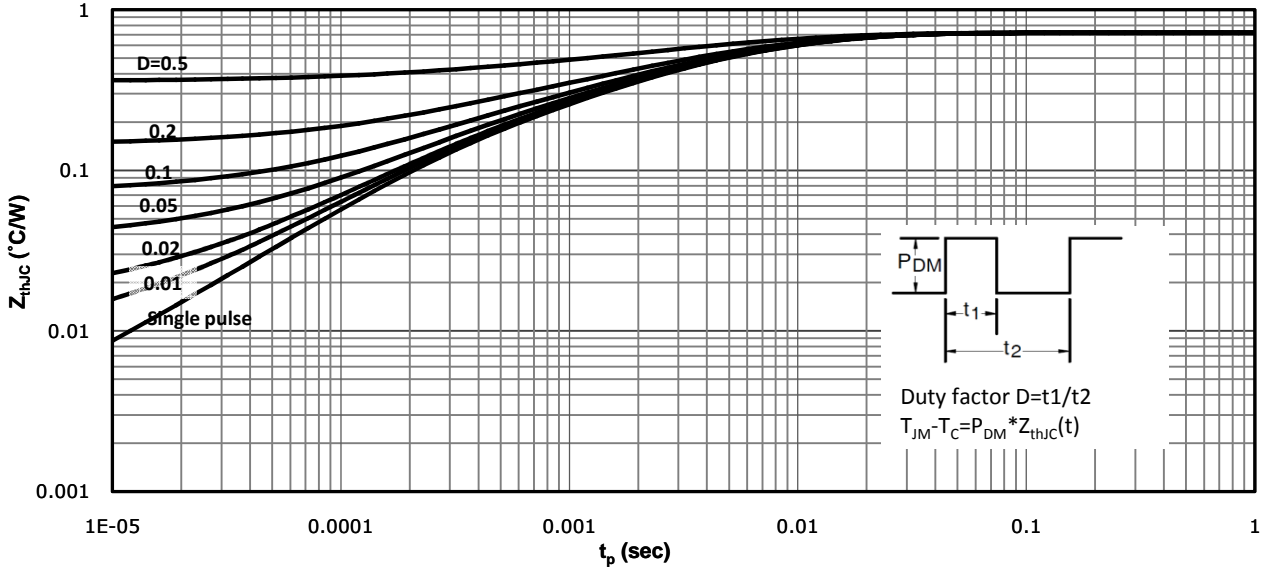
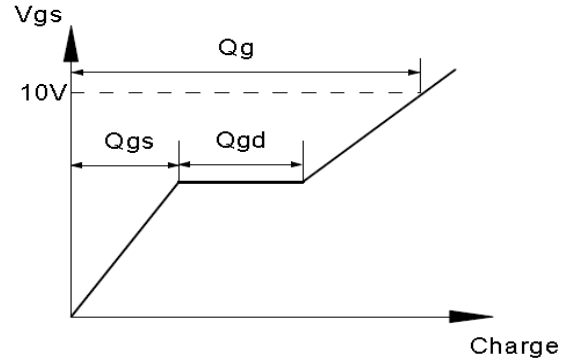
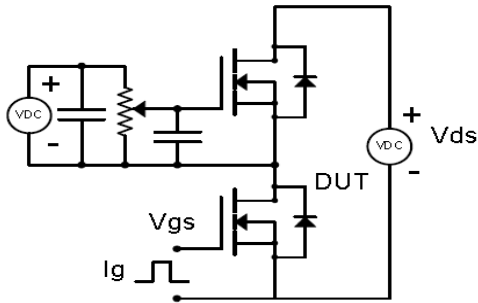


Fig 12: Max. Transient Thermal Impedance

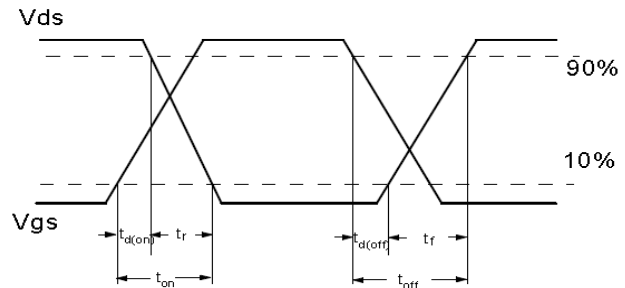
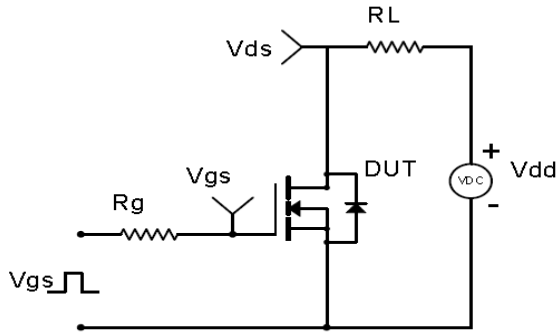


**Test Circuit & Waveform**

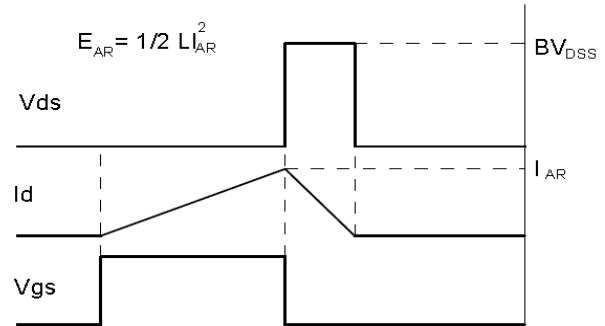
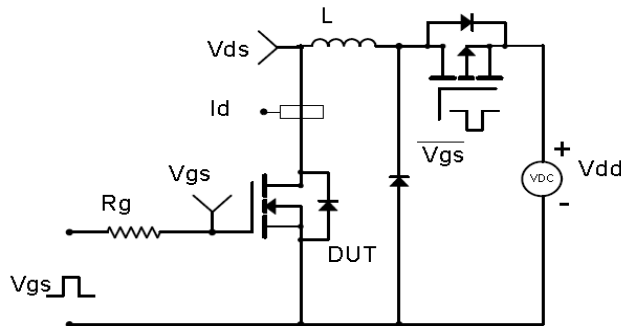
Gate Charge Test Circuit &amp; Waveform



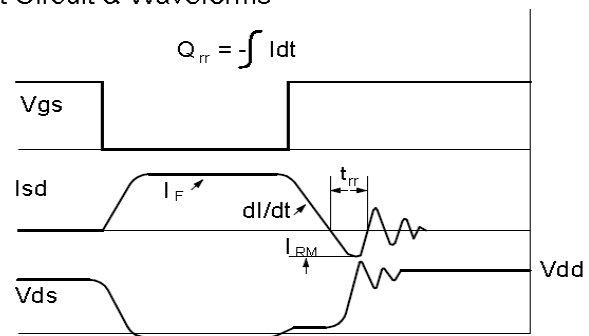
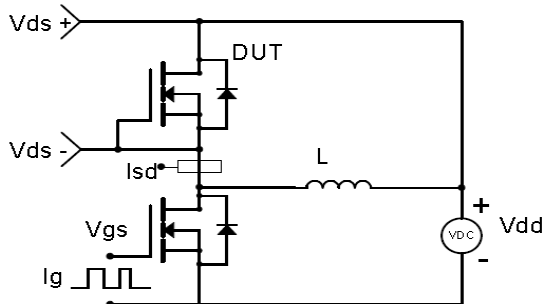
Resistive Switching Test Circuit &amp; Waveforms

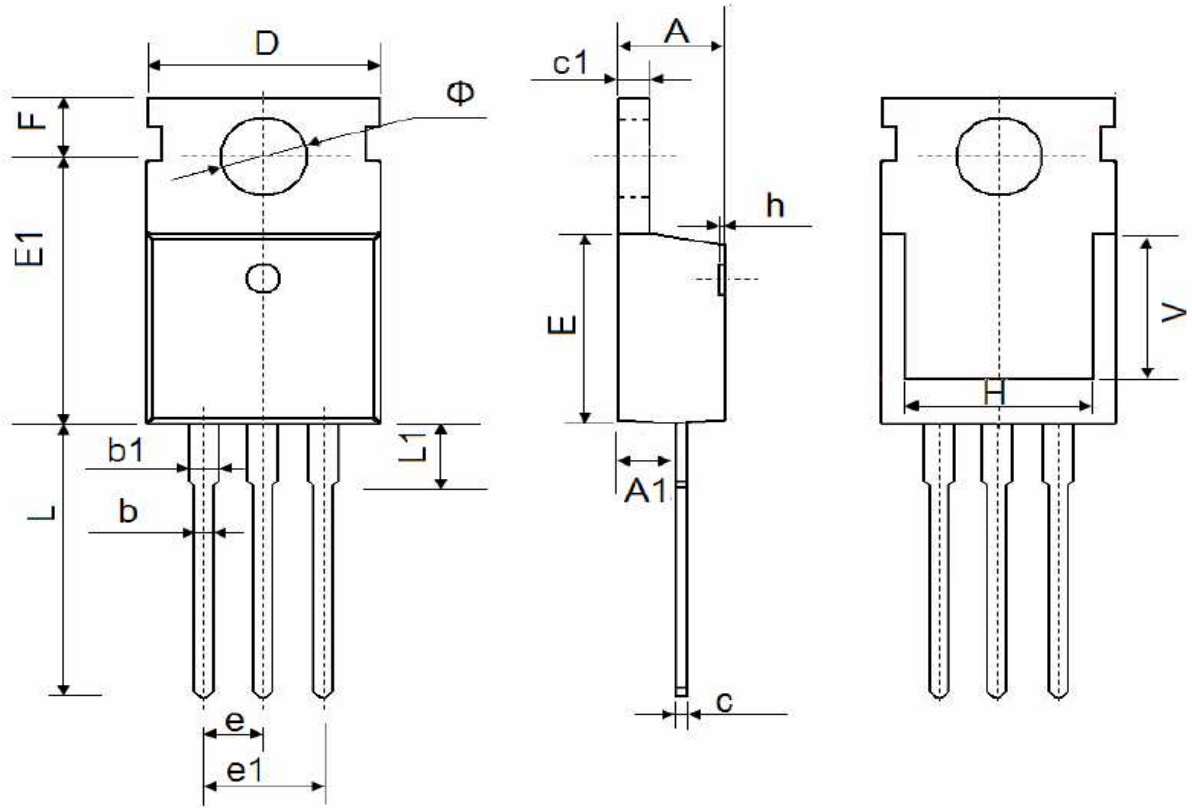


Unclamped Inductive Switching (UIS) Test Circuit &amp; Waveforms



Diode Recovery Test Circuit &amp; Waveforms

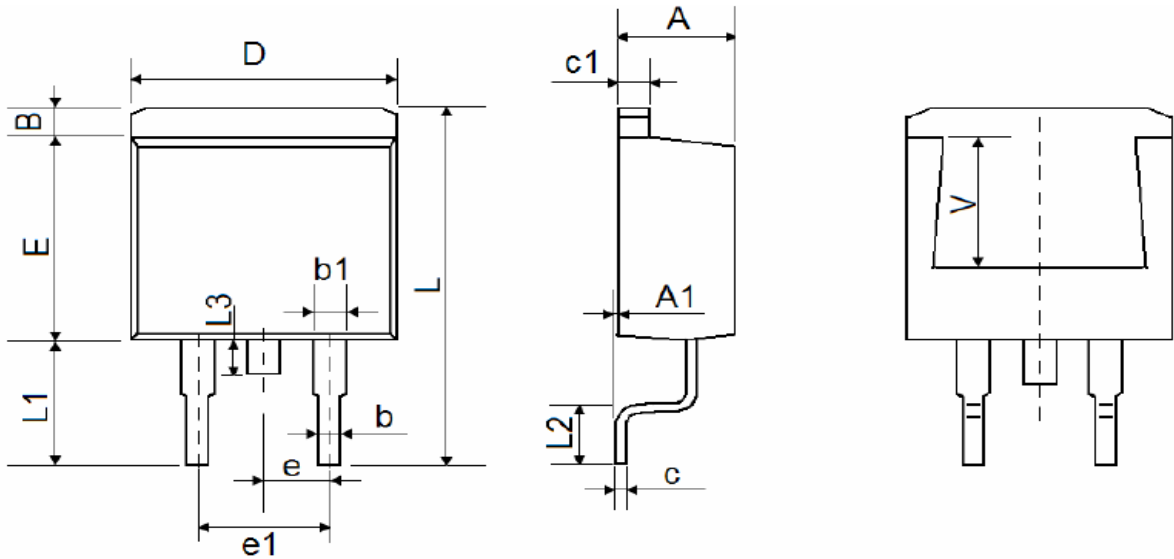


**Package Outline: TO-220-3L**


Symbol	Dimensions In Millimeters		Dimensions In Inches	
	Min.	Max.	Min.	Max.
A	4.4	4.6	0.173	0.181
A1	2.25	2.55	0.089	0.1
b	0.71	0.91	0.028	0.036
b1	1.17	1.37	0.046	0.054
c	0.33	0.65	0.013	0.026
c1	1.2	1.4	0.047	0.055
D	9.91	10.25	0.39	0.404
E	8.95	9.75	0.352	0.384
E1	12.65	12.95	0.498	0.51
e	2.540 Typ.		0.100 Typ.	
e1	4.98	5.18	0.196	0.204
F	2.65	2.95	0.104	0.116
H	7.9	8.1	0.311	0.319
h	0	0.3	0	0.012
L	12.9	13.4	0.508	0.528
L1	2.85	3.25	0.112	0.128
V	7.500 Ref.		0.295 Ref.	
Φ	3.4	3.8	0.134	0.15



## Package Outline: TO-263



Symbol	Dimensions In Millimeters		Dimensions In Inches	
	Min.	Max.	Min.	Max.
A	4.47	4.67	0.176	0.184
A1	0	0.15	0	0.006
B	1.17	1.37	0.046	0.054
b	0.71	0.91	0.028	0.036
b1	1.17	1.37	0.046	0.054
c	0.31	0.53	0.012	0.021
c1	1.17	1.37	0.046	0.054
D	10.01	10.31	0.394	0.406
E	8.5	8.9	0.335	0.35
e	2.540 Typ.		0.100 Typ.	
e1	4.98	5.18	0.196	0.204
L	15.05	15.45	0.593	0.608
L1	5.08	5.48	0.2	0.216
L2	2.34	2.74	0.092	0.108
L3	1.3	1.7	0.051	0.067
V	5.600 Ref.		0.220 Ref.	

## Revision History

Revision	Date	Major changes
1.0	2018-02-09	Release of formal version.

## Disclaimer

Unless otherwise specified in the datasheet, the product is designed and qualified as a standard commercial product and is not intended for use in applications that require extraordinary levels of quality and reliability, such as automotive, aviation/aerospace and life-support devices or systems.

Any and all semiconductor products have certain probability to fail or malfunction, which may result in personal injury, death or property damage. Customer are solely responsible for providing adequate safe measures when design their systems.

CRM(CQ) reserves the right to improve product design, function and reliability without notice.